

**Amendments to the Specification:**

Please amend paragraph [0012] as follows:

Fig. 5 shows a pump body suitable for adhesive silver flakes[[-]],

Please add the following new paragraph [0012.5] after paragraph [0012]:

Fig. 6 shows the inventive use of the device of the invention on a writing head for the application of adhesive onto a substrate to be equipped with a semiconductor chip.

Please add the following new paragraph [0015.5] after paragraph [0015]:

Fig. 6 illustrates the use of the device 45 on a writing head 46 for the application of adhesive onto a substrate 47 is to be equipped with a semiconductor chip. The adhesive is supplied through the writing nozzle 12. A semiconductor chip 48 mounted on substrate 47 by a portion of adhesive 49 shown on the right hand side.

BEST AVAILABLE COPY